

ABSTRACT

The present invention relates to a device for thermally treating workpieces, in particular printed circuit boards or the like that are equipped with electrical and electronic components, comprising at least
5 one process chamber in which at least one heating or cooling zone is formed or disposed, wherein a temperature-controlled gaseous fluid can be introduced into said heating or cooling zone, wherein the workpieces pass through the heating or cooling zone and heat is transferred particularly in a convective manner between the workpieces and the
10 temperature-controlled fluid, and comprising at least one temperature measuring element disposed in the process chamber, wherein at least one sensor element that has a defined mass is disposed in the process chamber, such that heat is convectively transferred between the sensor element and the fluid, and an apparatus is provided for cooling and/or
15 heating the sensor element, wherein the temperature of the sensor element can be measured by the temperature measuring element.

(Fig. 1)